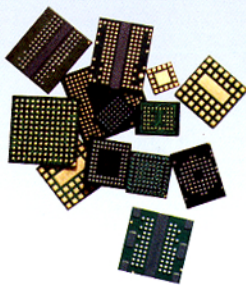


SAWING & PLACEMENT SYSTEM



**Dual Chuck
Sawing Process**

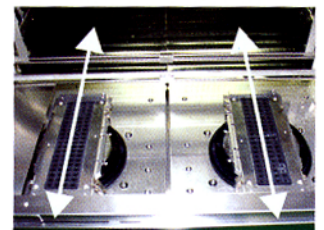


Model : SAWING & PLACEMENT – 20000D

- **High Productivity : 20,000 UPH**
- **Individually Operating Dual Chuck Sawing Process**
- **Multiple Unit Handling System**

- **Automatic Picker Pitch - Adjustment Function**

- High pick-up stability & success rate of unit placement



Individual Dual Chuck
Sawing Process

- **Universal Unit Picker Pad Applied(Patent Pending)**

- Conceptual innovation to handle for zero ball margin unit for BGA & BOC



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SAWING & PLACEMENT SYSTEM

■ World's NO.1 Technology & Market Share in Sawing Equipment

- Field proven machine reliability & stability
- Capability to handle, 2mm x 2mm package

■ Advanced Vision Inspection System

- Various inspection function with high resolution cameras

■ Enhanced Machine Features

- Easy & quick conversion
- Solution for handling warped substrate & bent tray
- Minimum down time & jamming (MTBA : 2~5 hours)
- Dual tray carrier system (no time delay in tray change)
- Drastic reduction of machine vibration
- Low cost of ownership
- Precise unit placement accuracy (no drop & no tilt)
- Easy to use graphical user interface (touch screen)

MTBA	2~5 hours	MTTA	max. 3 minutes
MTBF	168 hours	MTTR	max. 3 minutes



Semiconductor

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